DCN Num	hori	201612000	10	4	DCN	Dat		Doc 22 2016		
PCN Number: Title: Datasheet for			20161209004			PCN Date:		Dec. 22, 2016		
						Dai		Quality Convices		
Change		PCN Manager				De	pt:	Quality Services		
Change Ty	-		<del></del>	Docian			Mafar	Pump Cito		
Assembly Process			X	Design Data Sheet		H		Bump Site		
Assembly Process  Assembly Materials			싁	Part number change			Wafer Bump Material Wafer Bump Process			
Assembly Materials  Mechanical Specification			=	Test Site		H		Fab Site		
Packing/Shipping/Labeling			╡	Test Process		Ħ		Fab Materials		
				16361106633		一		Fab Process		
		N	ol	tification Details						
Description	n of Change	e:								
Texas Instruments Incorporated is announcing an information only notification etc.										
The product datasheet(s) is being updated as summarized below.  The following change history provides further details.										
<b>√i</b> Texa	s									
INST	Instruments ADS8319									
	SLAS600C -MAY 2008-REVISED DECEMBER 2016									
Changes from Revision B (December 2015) to Revision C										
Added ESD Ratings table, Recommended Operating Conditions table, Thermal Information table, Functional Block										
	Diagram, Application and Implementation section, Power Supply Recommendations section, and Layout section									
Changed all references of MSOP to VSSOP										
Changed all references of SON to VSON										
<ul> <li>Moved Operation temperature From: Electrical Characteristics table To: Recommended Operating Conditions table 4</li> <li>Changed Thermal impedance, R<sub>eJA</sub>, values in Thermal Information table From: 180°C/W To: 107.5°C/W (VSSOP) and From: 70°C/W To: 87.2°C/W (VSON)</li></ul>										
The detacle of words and the characters										
The datasheet number will be changing Device Family			Change From:				Ch	ango Tor		
ADS8319				SLAS600B				ange To: AS600C		
JERSON SERSON								ASOUC		
These changes may be reviewed at the datasheet links provided. <a href="http://www.ti.com/product/ADS8319">http://www.ti.com/product/ADS8319</a>										
Reason for Change:										
To more ac	curately refle	ect device chara	ct	eristics.						
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):										
No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.										
Changes t	o product i	dentification re	es	ulting from this PCI	N:					
None.										
Product A	ffected:									
ADS8319IB		ADS8319IBDGST		ADS8319IBDI	RCR	АГ	S8319IB	BDRCT		
ADS8319ID		ADS8319IDGST		ADS8319IDR0		<u> </u>	3222010			
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For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

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